

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
80V	8mΩ @ V _{GS} = 10V	13A
	9.5mΩ @ V _{GS} = 6V	12A
	12mΩ @ V _{GS} = 4.5V	11A

Features and Benefits

- High Conversion Efficiency
- Low R_{DS(ON)} – Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact_us) or your local Diodes representative.
<https://www.diodes.com/quality/product-definitions/>

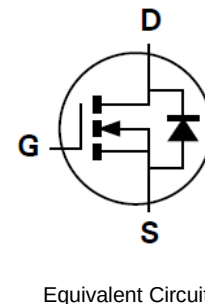
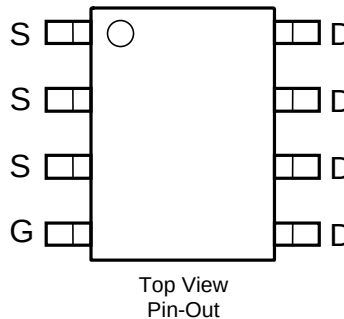
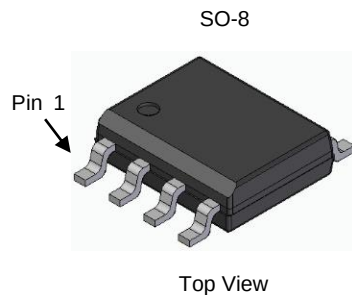
Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- High Frequency Switching
- Synchronous Rectification
- DC-DC Converters

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.074 grams (Approximate)

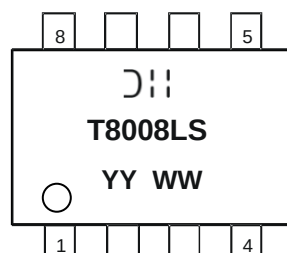


Ordering Information (Note 4)

Part Number	Case	Packaging
DMT8008LSS-13	SO-8	2,500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



DII = Manufacturer's Marking
T8008LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 19 = 2019)
WW = Week (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	80	V
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = 10V	T _A = +25°C	I _D	13	A
	T _A = +70°C	I _D	10	A
	T _C = +25°C	I _D	32	A
	T _C = +70°C	I _D	26	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)		I _{DM}	110	A
Maximum Continuous Body Diode Forward Current (Note 6)		I _S	10	A
Pulsed Body Diode Forward Current (10μs Pulse, Duty Cycle = 1%)		I _{SM}	110	A
Avalanche Current, L = 0.3mH (Note 9)		I _{AS}	27	A
Avalanche Energy, L = 0.3mH (Note 9)		E _{AS}	109	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	94	°C/W
Total Power Dissipation (Note 6)	P _D	2.2	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	58	°C/W
Thermal Resistance, Junction to Case (Note 6)	R _{θJC}	10	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	80	—	—	V	V _{GS} = 0V, I _D = 1mA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 64V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±1	μA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1.3	—	2.8	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	6	8	mΩ	V _{GS} = 10V, I _D = 10A
		—	7	9.5		V _{GS} = 6V, I _D = 10A
		—	8.3	12		V _{GS} = 4.5V, I _D = 6A
		—	—	—		V _{GS} = 4.5V, I _D = 6A
Diode Forward Voltage	V _{SD}	—	0.8	1.2	V	V _{GS} = 0V, I _S = 20A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	2840	—	pF	V _{DS} = 40V, V _{GS} = 0V, f = 1MHz
Output Capacitance	C _{oss}	—	797	—		
Reverse Transfer Capacitance	C _{rss}	—	42	—		
Gate Resistance	R _g	—	1.7	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	24	—	nC	V _{DD} = 40V, I _D = 2A
Total Gate Charge (V _{GS} = 10V)	Q _g	—	47	—		
Gate-Source Charge	Q _{gs}	—	7	—		
Gate-Drain Charge	Q _{gd}	—	11	—		
Turn-On Delay Time	t _{d(ON)}	—	6	—	ns	V _{DD} = 40V, V _{GS} = 10V, I _D = 2A, R _g = 1.6Ω
Turn-On Rise Time	t _r	—	6	—		
Turn-Off Delay Time	t _{d(OFF)}	—	27	—		
Turn-Off Fall Time	t _f	—	44	—		
Body Diode Reverse Recovery Time	t _{RR}	—	43	—	ns	I _F = 2A, di/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _R	—	59	—	nC	

- Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to product testing.
 9. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.

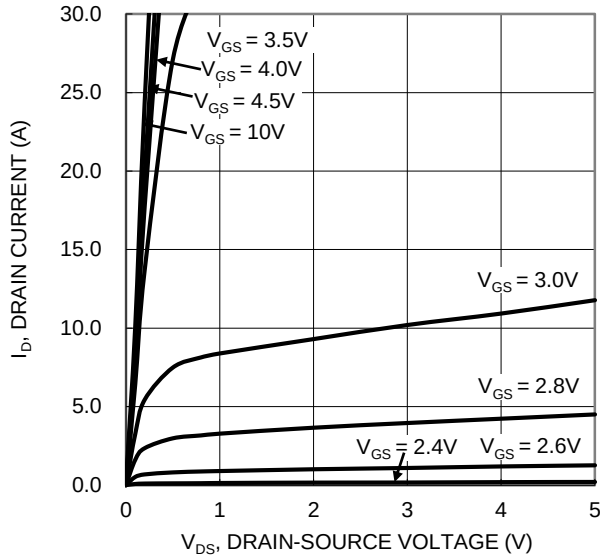


Figure 1. Typical Output Characteristic

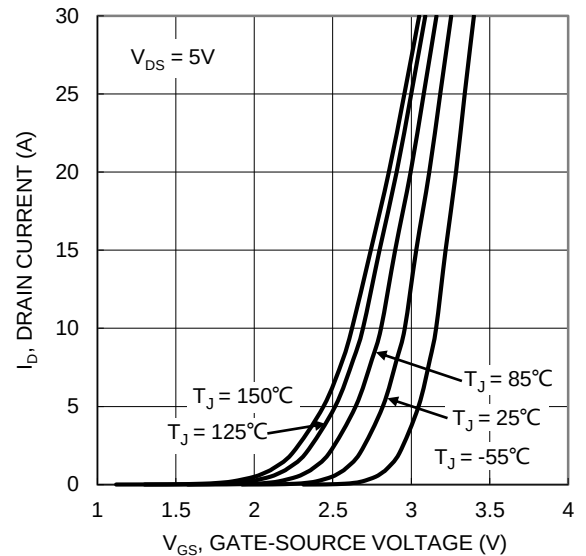


Figure 2. Typical Transfer Characteristic

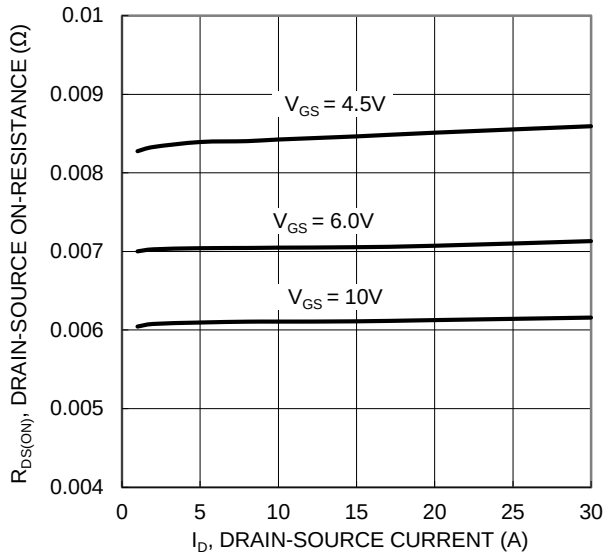


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

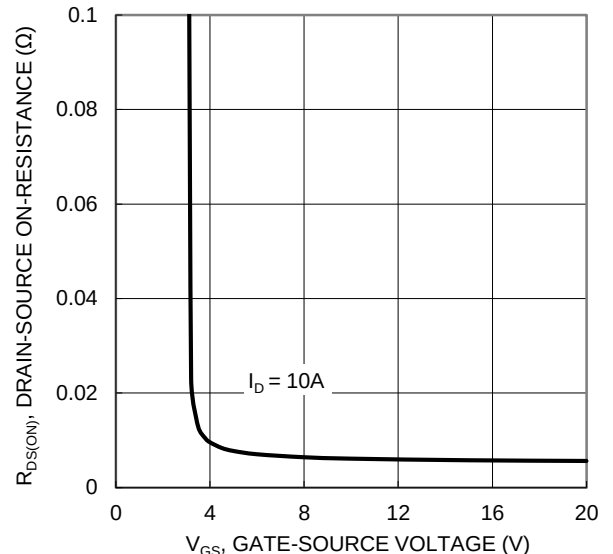


Figure 4. Typical Transfer Characteristic

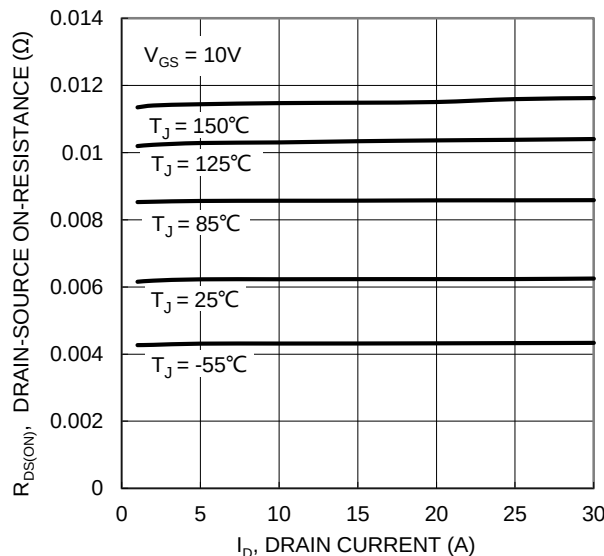


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

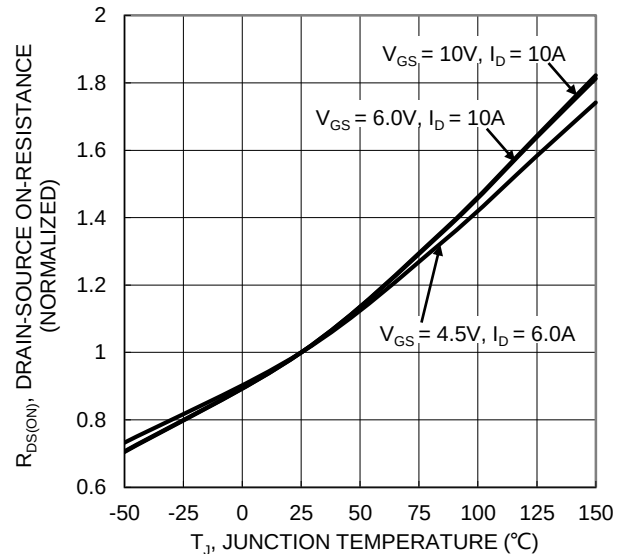
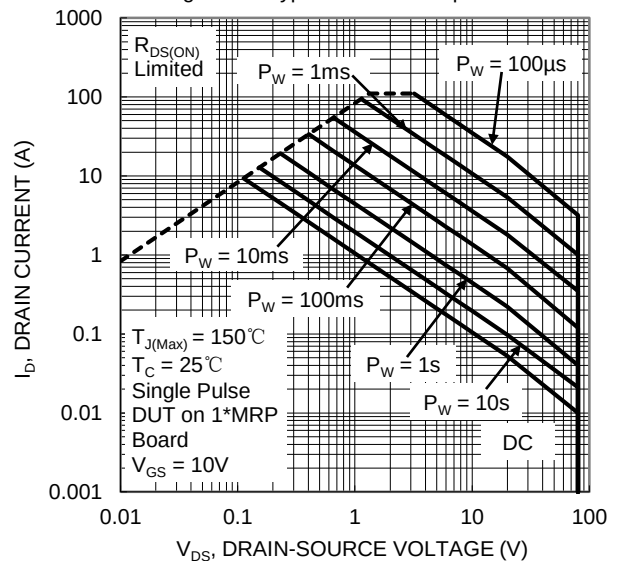
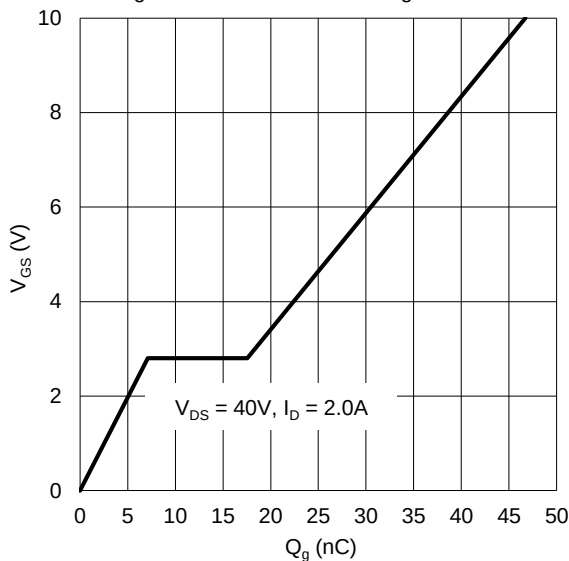
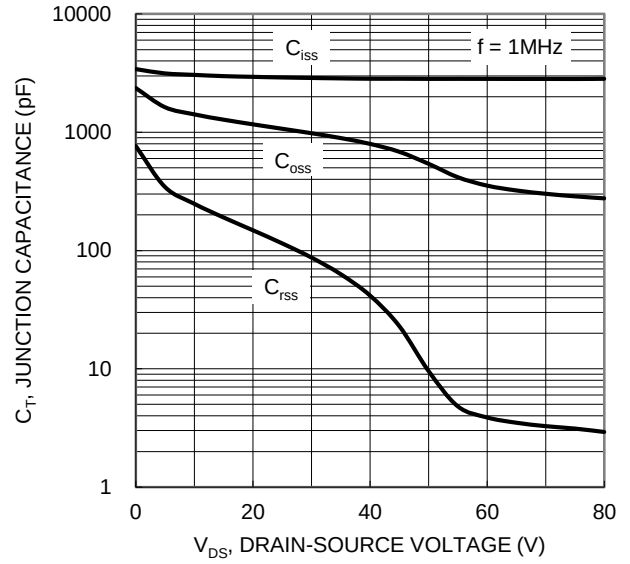
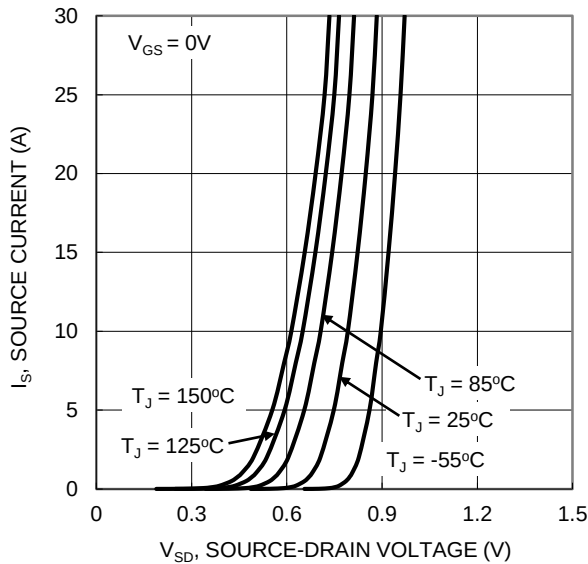
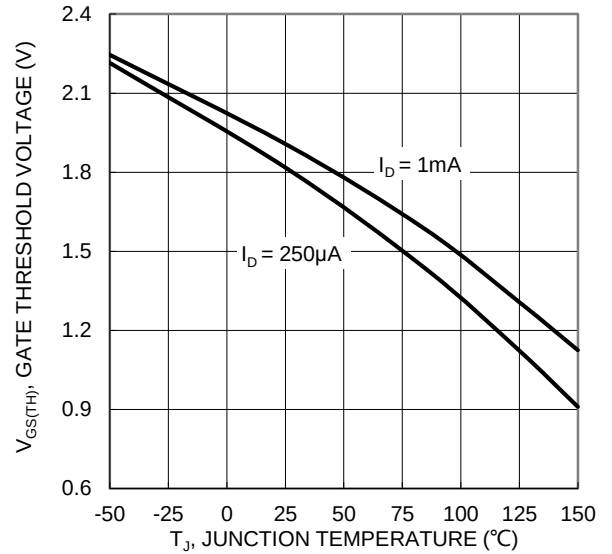
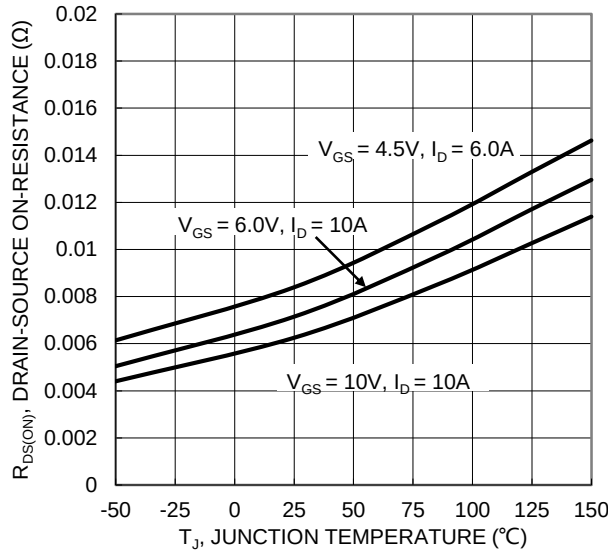


Figure 6. On-Resistance Variation with Junction Temperature



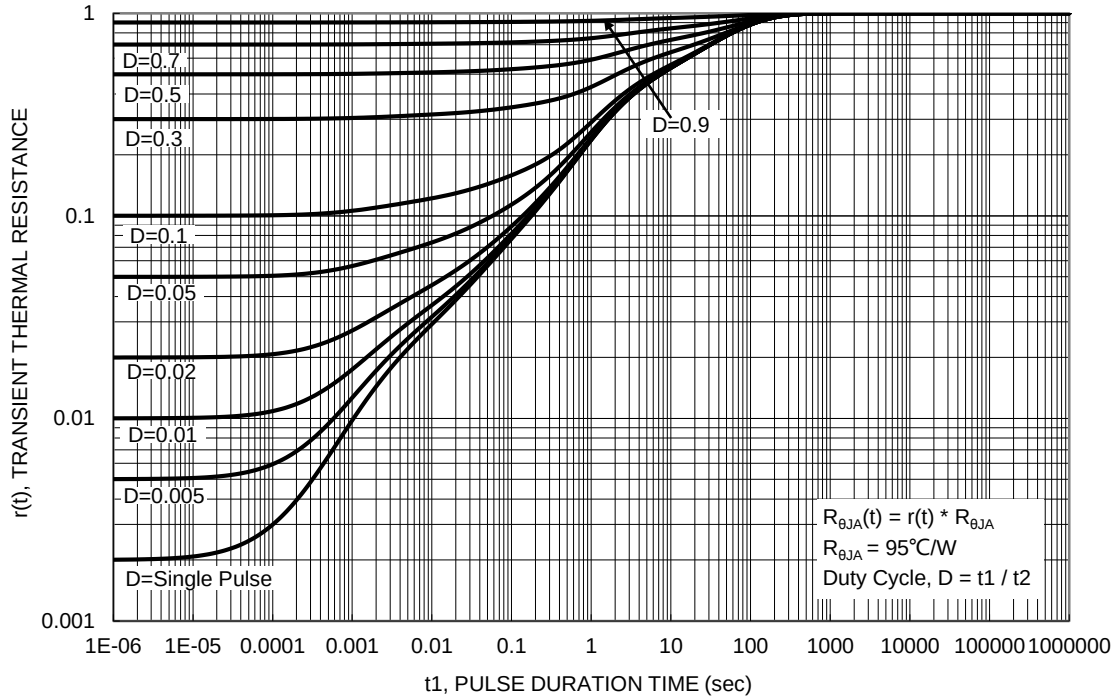
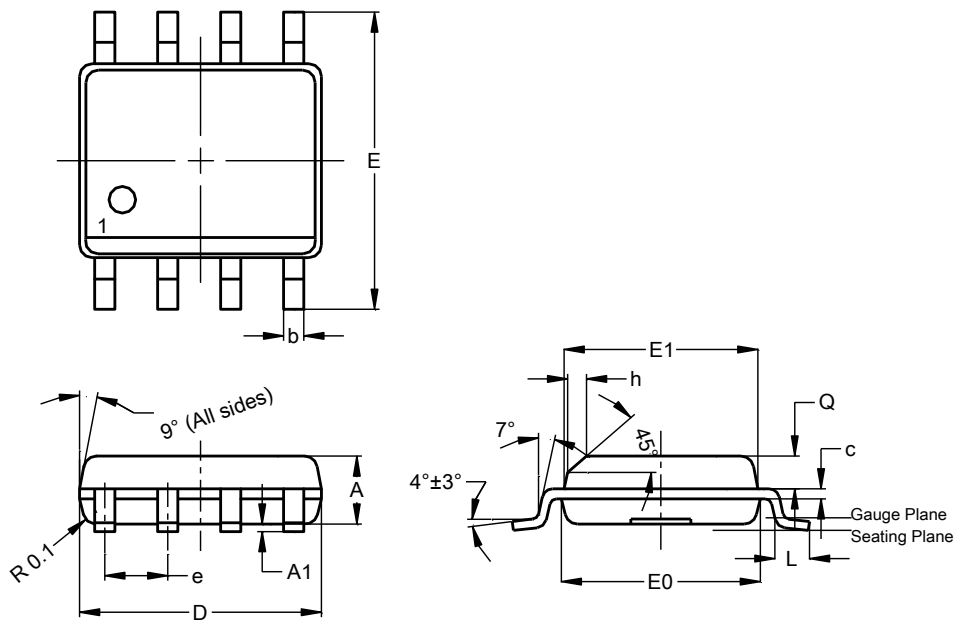


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8

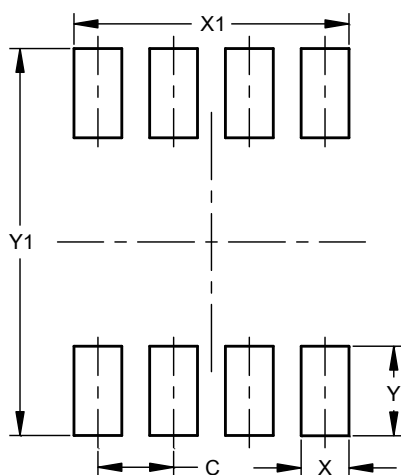


SO-8			
Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	-	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50

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